



an Open Access Journal by MDPI

Recent Advances in Soft Electronics and Ionics

Guest Editor:

Prof. Dr. Reza Montazami

Department of Mechanical
Engineering, 2094 Black
Engineering Building, Iowa State
University, Ames, IA 50011-2023,
USA

Deadline for manuscript
submissions:

closed (15 March 2020)

Message from the Guest Editor

Dear Colleagues,

As electronic devices are getting more and more integrated into our everyday activities, the need to minimize mechanical mismatch between electronic devices (rigid by nature) and biological systems (soft by nature) is becoming more eminent. There is a broad range of applications for soft, flexible, and stretchable electronic devices in a variety of fields of research, including biomedical, sensing, actuation, energy storage, energy harvesting, hardware security, military, athletics, and rehabilitation. The deformability of such electronic devices is, however, counterintuitive to the physical and dimensional stability that is required for the stable operation of electronic devices.

The ultimate goal of this Special Issue is to gather and disseminate the most innovative, impactful, and recent advances and discoveries in the field of soft electronic and ionic devices. Communications, full papers, and review papers are all welcome.



mdpi.com/si/20955

Special Issue



an Open Access Journal by MDPI

Editors-in-Chief

Prof. Dr. Maryam Tabrizian

1. Department of Biomedical Engineering, Faculty of Medicine and Health Sciences, McGill University, Montreal, QC H3A 2B6, Canada

2. Faculty of Dentistry and Oral Health Sciences, McGill University, 3640 Rue University, Montreal, QC H3A 0C7, Canada

Prof. Dr. Yuguang Ma

State Key Laboratory of Luminescent Materials and Devices, South China University of Technology, Guangzhou 510640, China

Message from the Editorial Board

Materials (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, SCIE (Web of Science), PubMed, PMC, Ei Compendex, CaPlus / SciFinder, Inspec, Astrophysics Data System, and other databases.

Journal Rank: JCR - Q2 (Metallurgy and Metallurgical Engineering) / CiteScore - Q1 (Condensed Matter Physics)

Contact Us

Materials Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/materials
materials@mdpi.com
[X@Materials_Mdpi](https://twitter.com/Materials_Mdpi)